

3D Integrated Front Side Illuminated Photon-to-Digital Converters: Status and Applications

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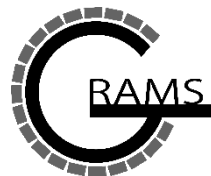
³Teledyne-Dalsa, Bromont, Canada

ISSW2020 – Edinburgh, Scotland

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What is a Photon-to-Digital Converter - PDC

A Photon-to-Digital Converter (PDC) is a SPAD array read out by a CMOS pixelated circuit with embedded digital signal processing.

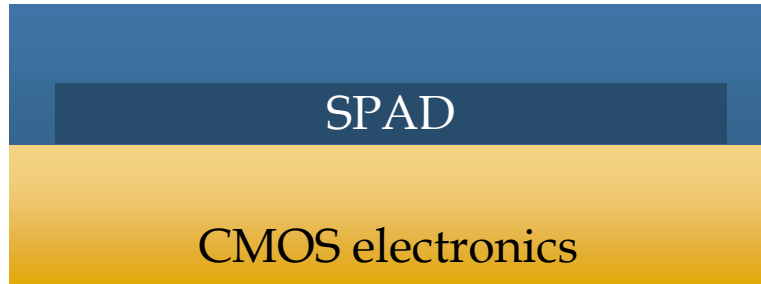
- The name “PDC” is inspired from “Analog-to-Digital Converter”.
- Digital signal processing can be simple or advanced:
 - Photon/Triggered SPAD counts,
 - Time stamping,
 - Timing skew correction, sorting, dark count filter,
 - Advanced algorithms embedded in CMOS for online processing (e.g.: Gauss-Markov estimator).

-Embedded time of arrival estimation for digital silicon photomultipliers with in-pixel TDCs, Lemaire, Nolet, Dubois, C. Therrien, Pratte, Fontaine, NIM:A, Vol. 959, 2020, ISSN 0168-9002, <https://doi.org/10.1016/j.nima.2020.163538>

-A 256 Pixelated SPAD readout ASIC with in-Pixel TDC and embedded digital signal processing for uniformity and skew correction, Nolet, Lemaire, Dubois, Roy, Carrier, Samson, Charlebois, Fontaine, Pratte, NIM:A, Vol. 949, 2020, ISSN 0168-9002, <https://doi.org/10.1016/j.nima.2019.162891>

Photon-to-Digital Converter Implementation Schemes

Back side illumination



Front side illumination



Why is front side illuminated PDC relevant?

For optimal Single Photon Timing Resolution (SPTR)

Ultimate target: sub 10-ps SPTR (SPAD + CMOS readout)

SPAD designed for:

- Minimum drift between photoelectron interaction and the high E field avalanche region
- Minimum drift time variation (= jitter)
- Uniformed E field
- Spectral sensitivity < 650 nm; UV and VUV also of interest (more later in this talk)

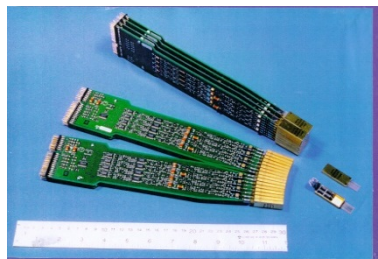
Why Targeting 10 ps Single Photon Timing Resolution?

For Medical Imaging



Medical Imaging @ Sherbrooke: Positron Emission Tomography

BGO Scanner (1995-2009) ✓ 1st APD-based PET scanner in the world



8-channels front-end board

2.1 mm
~14 μ l

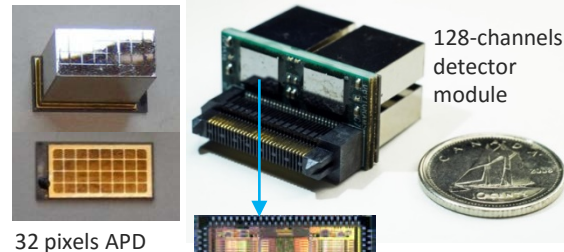
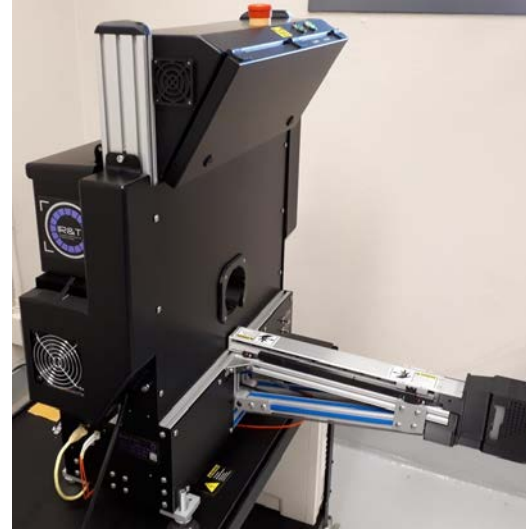
LabPET™(2005) ✓ 1st APD-based commercial PET scanner



64-channels front-end board and digitizer

1.35 mm
~2.4 μ l

LabPET II™(2015) ✓ 1st Commercial scanner with sub-mm resolution

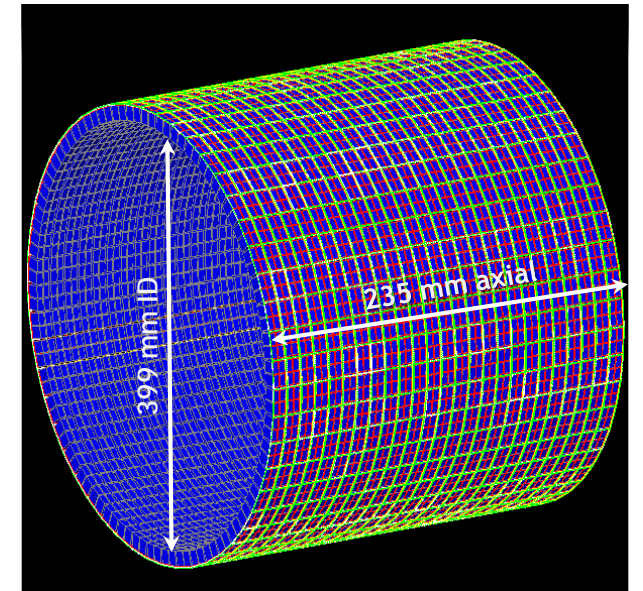


0.73 mm
~0.4 μ l



<https://imagingrt.com/>

UHR™(2020) ✓ Brain scanner



1,008 modules
129,024 channels

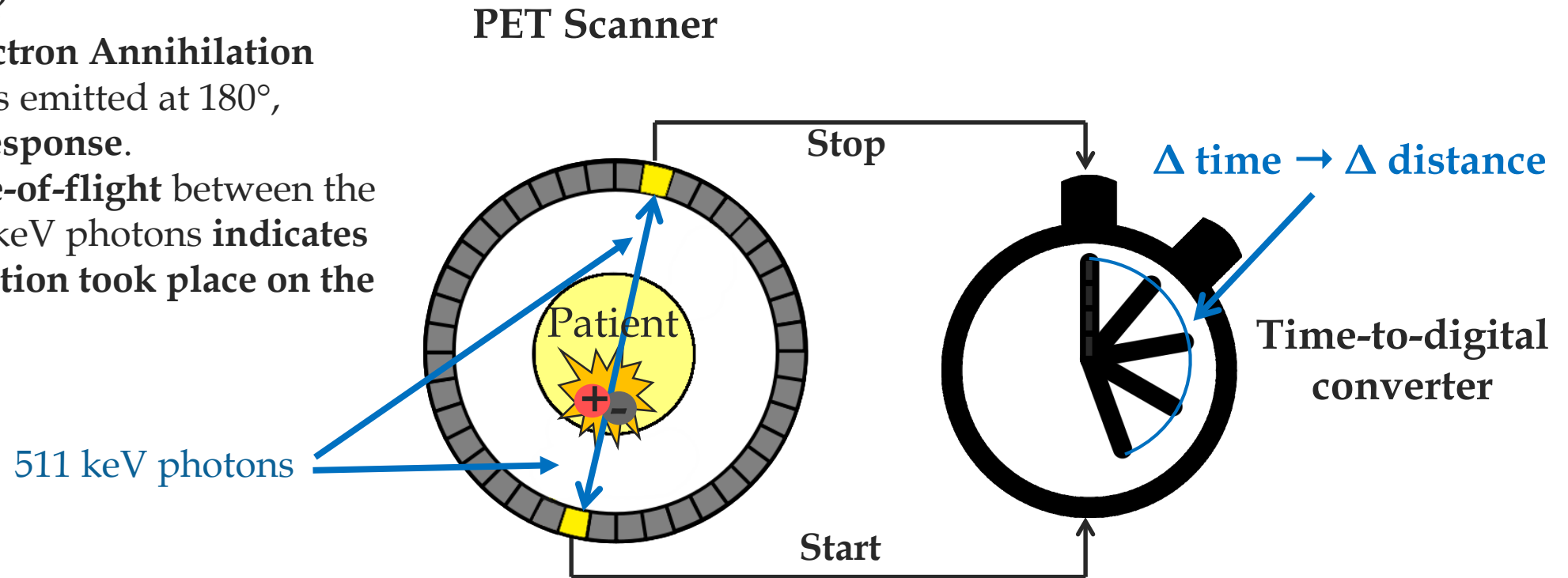
1.3 mm
~2.1 μ l

Time-of-Flight in Positron Emission Tomography Medical Imaging

How does PET works?

Positron-Electron Annihilation

- 2 x 511 keV photons emitted at 180°, creating a **line of response**.
- Measuring the **time-of-flight** between the arrival of both 511 keV photons **indicates where the annihilation took place on the line of response**



10 ps FWHM coincidence timing precision => 1.5 mm spatial precision

PDC **Single Photon Timing Resolution** required: < 10 ps FWHM

Advantages of Time-of-Flight Positron Emission Tomography

Time-of-Flight:

- improve image's contrast,
 - lower radiotracer dose,
 - real-time imaging (reconstruction-less),
 - pediatric care,
 - ...
-
- Roadmap toward the 10 ps time-of-flight PET challenge, Physics in Medicine & Biology, 2020, <http://iopscience.iop.org/10.1088/1361-6560/ab9500>
 - <https://the10ps-challenge.org/>

Photon-to-Digital Converters for Particle Physics

...to Answer Fundamental Questions about Matter and
our Universe.



PDC to Enable Neutrino Physics and Dark Matter Discovery

- Liquid argon (87 K) and liquid xenon (165 K)
- Cryogenic operation - PDC operated in noble liquid
 - Low power
- Large area (5 to 200 m²)
- VUV sensitivity required
 - Liquid argon: 125 nm (without wavelength shifter)
 - Liquid xenon: 178 nm

Is the Neutrino its own Antiparticle (Majorana Particle) ? Revolutionizing the Standard Model of Particle Physics

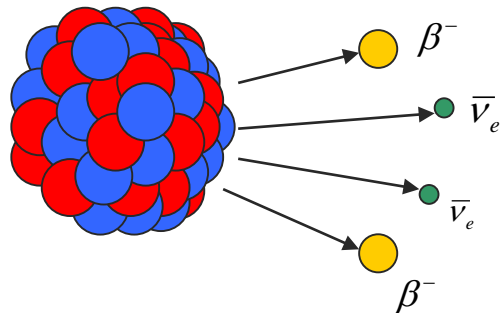
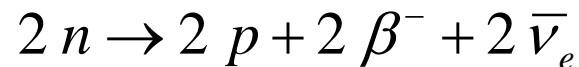
Following Art McDonald' 2015 Nobel prize, we know that **neutrino** has **mass**,
but the actual mass is **unknown**...

A **measurement** that would shed light both on the **actual mass** of a neutrino and the **origin** of this mass is the
detection of a theoretical and extremely rare process known as
neutrino-less double beta decay ($0\nu\beta\beta$).

Additionally, observation of this process could shed light on another fundamental mystery: why in a **Big Bang** that
started with **pure energy** we ended up with a **universe** composed almost entirely of **matter** but no **anti-matter**?

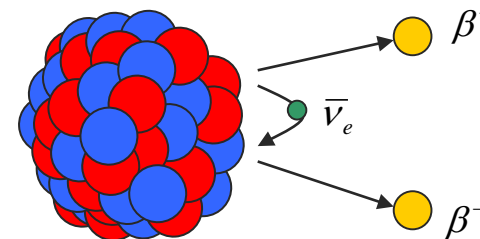
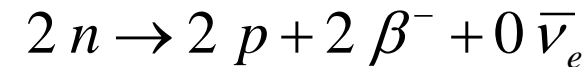
Standard model

2ν double β - decay



New physics

0ν double β - decay



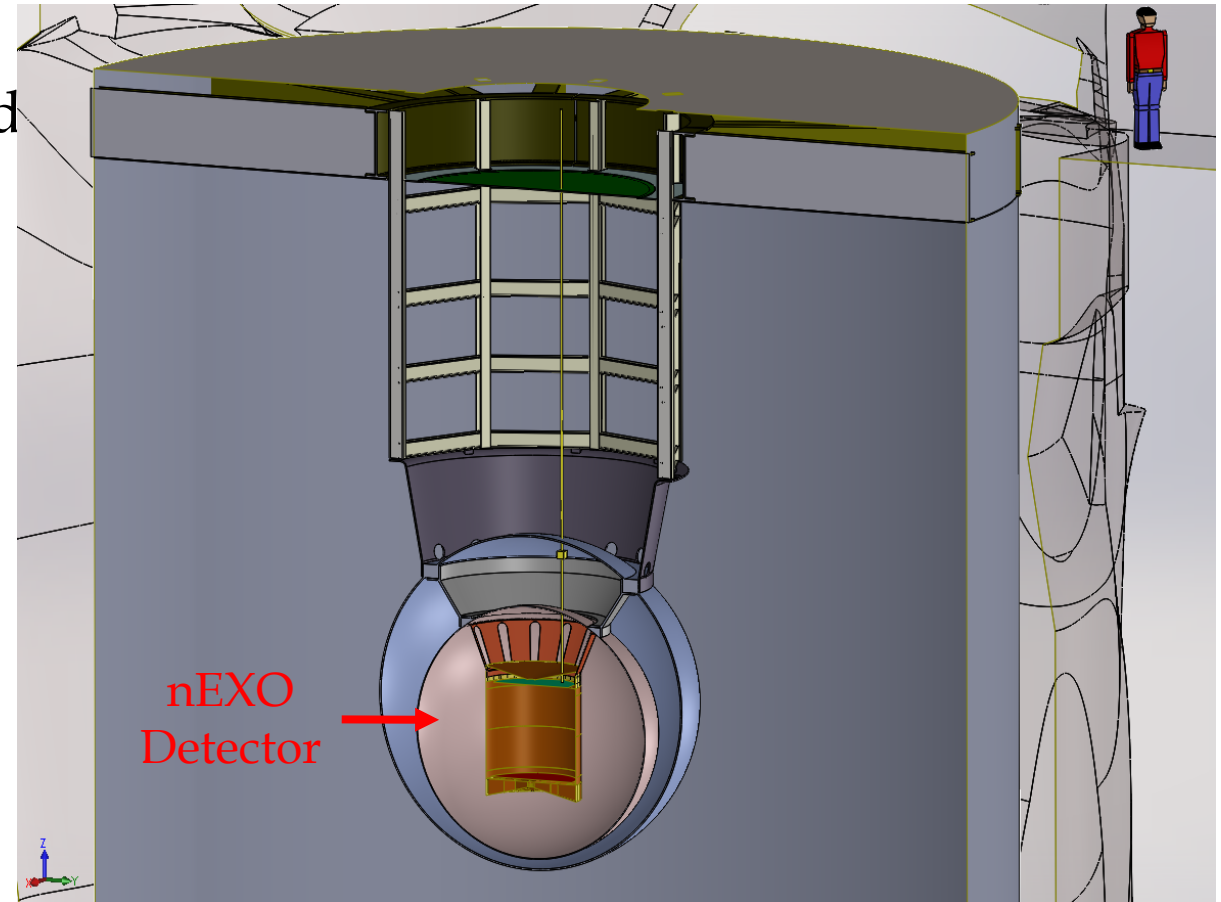
Lepton number
conservation violated

nEXO



nEXO – the next Enriched Xenon Observatory

- 2 km underground (SNOLAB, Sudbury, Canada, is considered)
 - Earth crust shields for cosmic background
- Measures
 - secondary electrons
 - LXe scintillation light (**178 nm**)
- Detector volume
 - 1.3 m \varnothing \times 1.3 m
 - 5 t of enriched liquid Xenon-136
 - 165 K
 - **4.5 m² of photodetectors**
 - **100 W** power budget



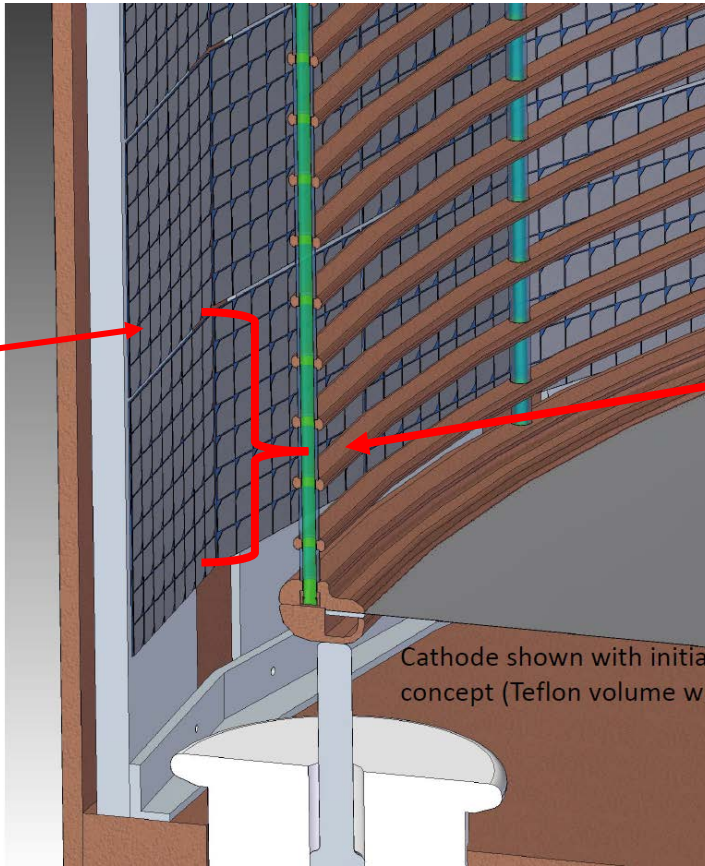
2016/06/27 nEXO Collaboration Meeting document - Allen House - Vessels/Mechanics summary

nEXO – Sherbrooke’s Goal : PDC Photodetector Tiles

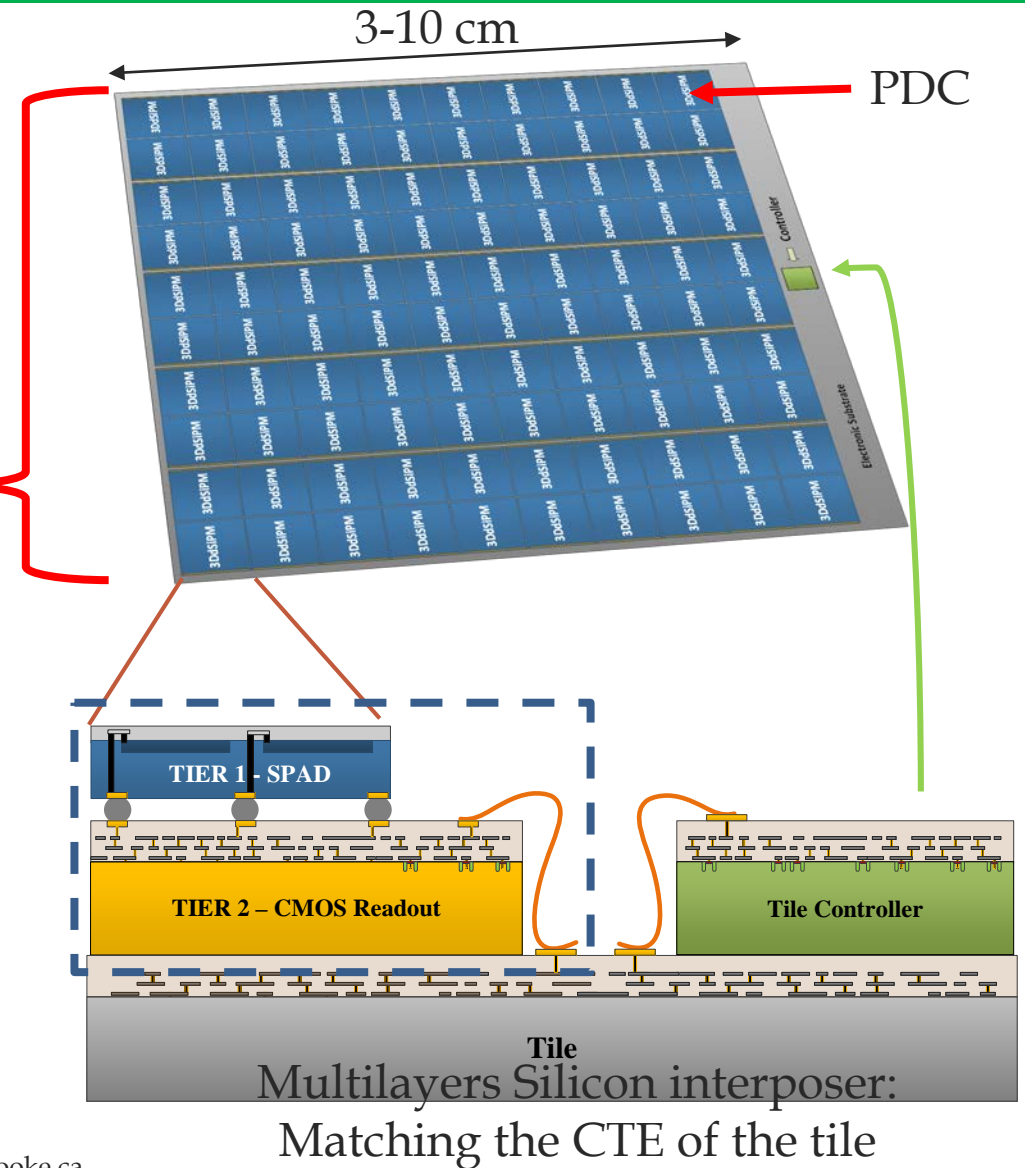
Photodetector barrel

Baseline design:
Analog SiPM (FBK or Hamamatsu)

Sherbrooke’s proposal:
VUV-PDC on Silicon Interposer



2016/06/27 nEXO Collaboration Meeting document - Allen House - Vessels/Mechanics summary



Development of the PDC Technology:

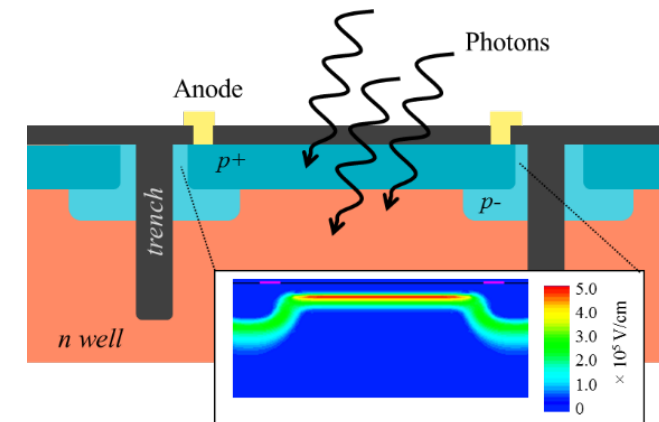
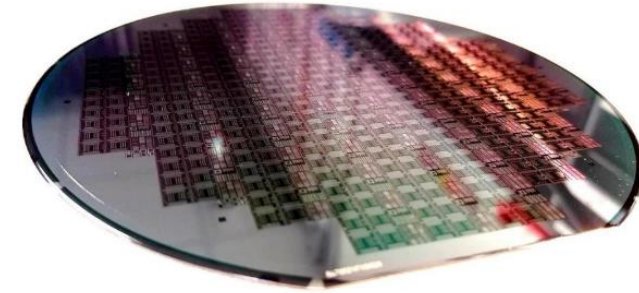
Parallel R&D on SPAD, 3D Vertical Integration and CMOS readout circuits



Development of the PDC Technology: The SPAD Array

SPAD R&D and Characterization

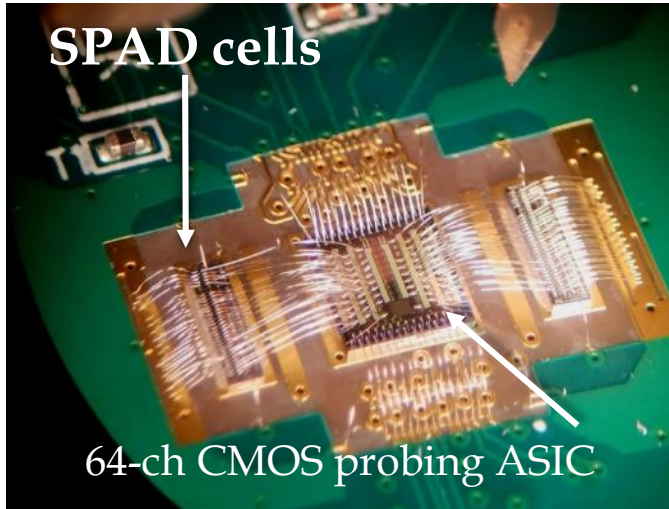
- 150 mm wafer (custom process using Teledyne-DALSA CCD production line)
- 1x1 to 5x5 mm² SPAD array
- 50-100 μm diameter **front-side illuminated** shallow P+N type SPAD ($\sim 0.4 \mu\text{m}$ depth)
- 4 μm width / 22 μm depth optical/electrical isolation trench (highly doped polysilicon filling)
- 2D process for parallel SPAD development
- New SPAD received March 2020: Covid-19 is delaying testing



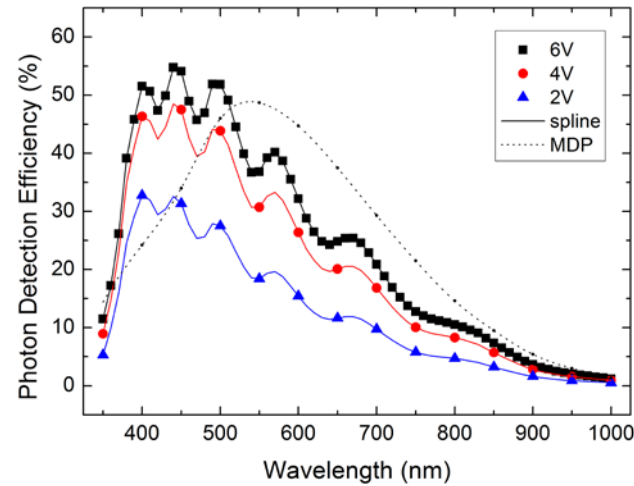
Front-side illuminated shallow p⁺n type SPAD

SPAD R&D and Characterization

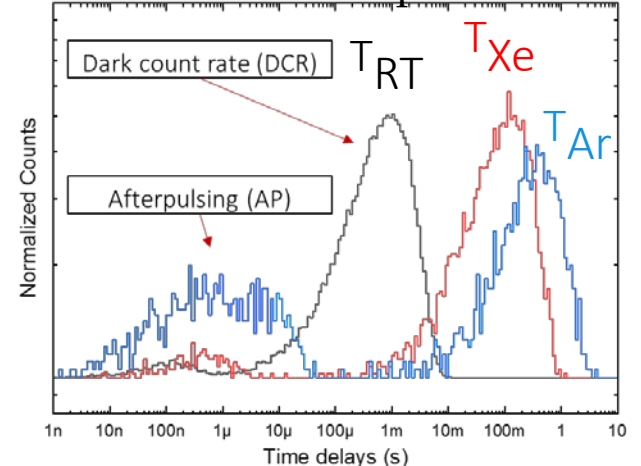
2D SPAD development platform



Photon Detection Efficiency

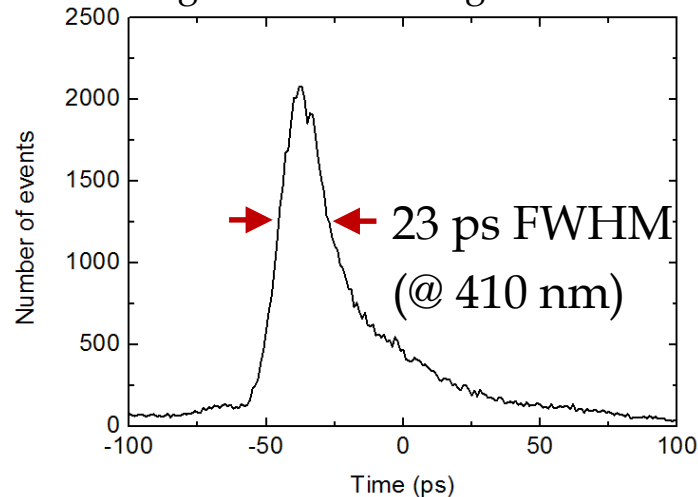


Noise vs temperature



Time-delay histogram between two consecutive counts

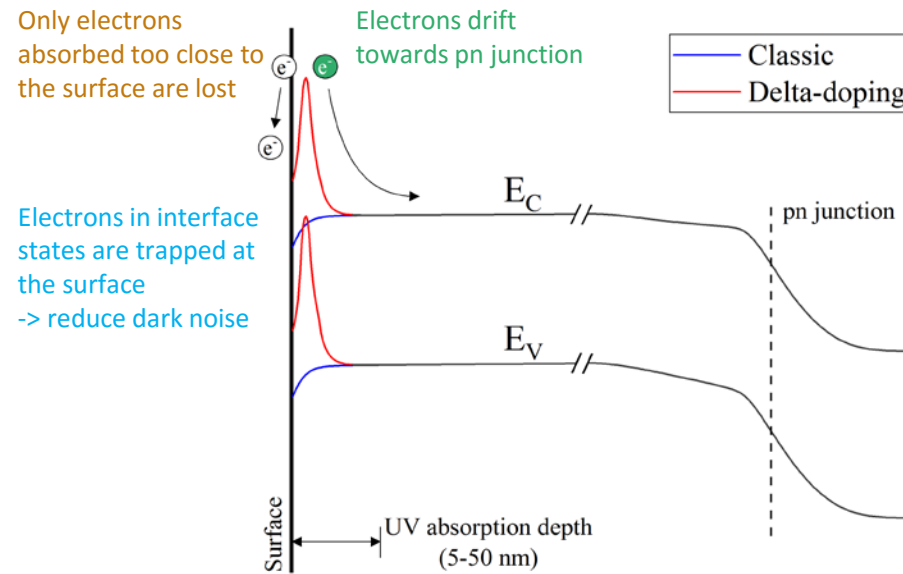
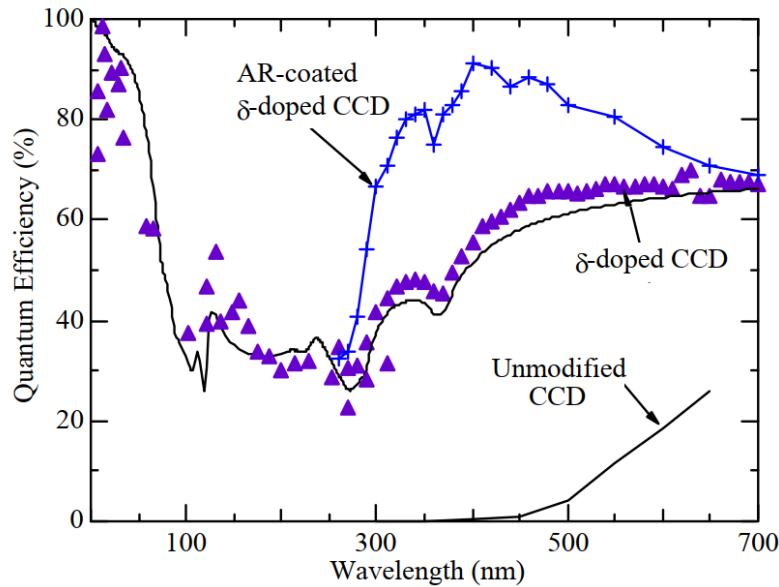
Single Photon Timing Resolution



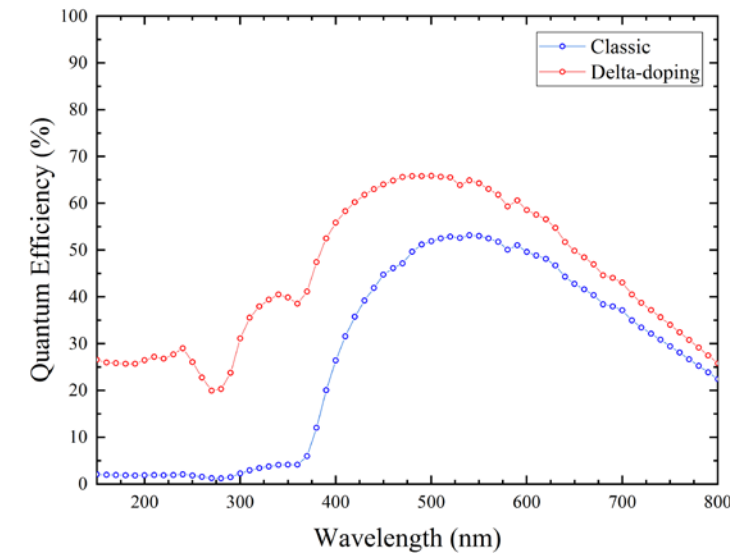
SPAD array DCR:
 $\sim 1000 \text{ Hz/mm}^2$
 (assuming $38 \mu\text{m}$ SPAD with 60% FF)

VUV Sensitivity Enhancement for Liquid Argon and Liquid Xenon

- Penetration depth @ 175 nm = 5.8 nm
- Delta-doping: surface energy band engineering to cause electron drift toward the high field avalanche region
- Delta doping: increase internal quantum efficiency (~100% IQE in CCDs ▲)
- Delta doping + anti-reflective coating (+) : major PDE improvement
- UdeS-TRIUMF-Lawrence Berkeley Lab collaboration « Towards high efficiency single VUV photon



Simulation of energy bands with delta-doping



Simulation of SPAD internal efficiency with delta-doping

Delta-doped back-illuminated CMOS imaging arrays: progress and prospects.
M.E. Hoenk (In Infrared Systems and Photoelectronic Technology IV 2009)

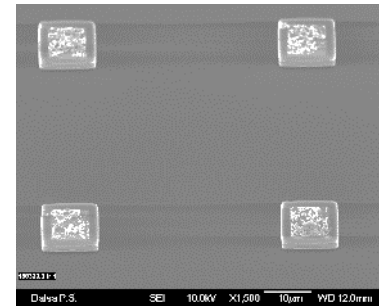
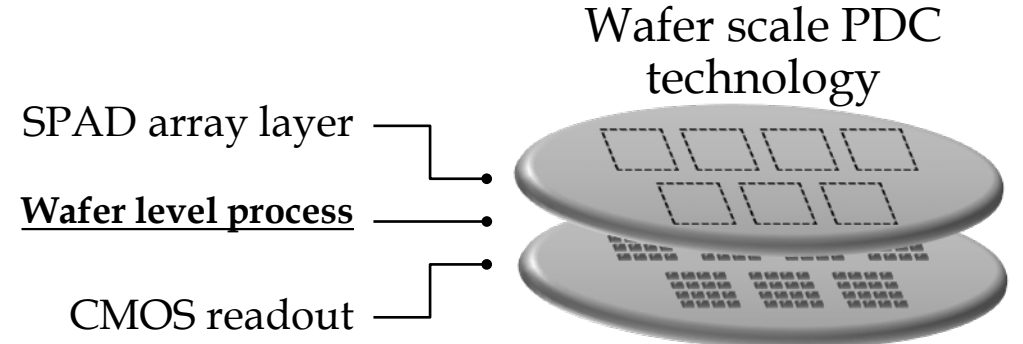
Development of the PDC Technology: The 3D Vertical Integration Process



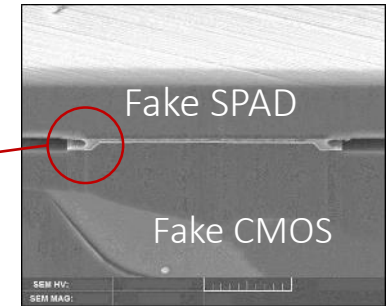
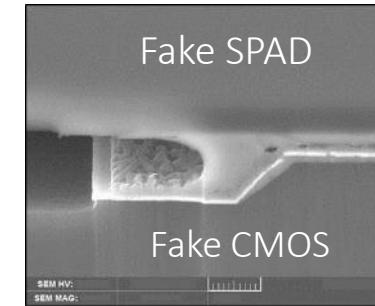
Photon-to-Digital Converter : Al-Ge 3D Integration Process and Resistivity Measurement

3D Process overview :

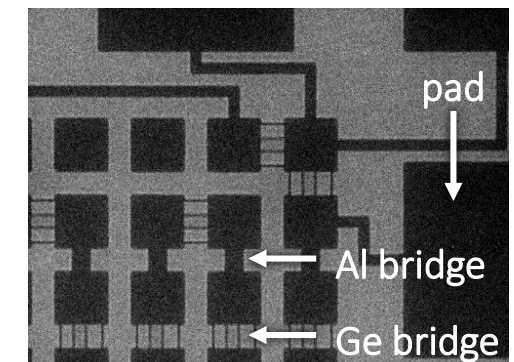
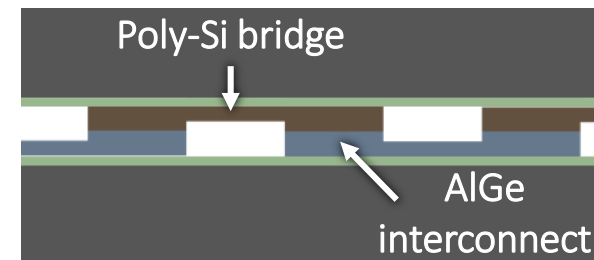
- ✓ SPAD array and trenches (skipped for 3D 1st run)
 - ✓ Direct bonding on handle wafer
 - ✓ Back side thinning + Back side Ge interconnect
 - ✓ AlGe wafer-to-wafer bonding with fake CMOS
 - Front side relief (handle removing)
 - CMOS pads opening, dicing
-
- Measurement of AlGe interconnect $<1 \Omega$
 - Towards completion of 3D validation samples



Ge interconnects :
10x10 um size
50 um pitch



AlGe "solder" (eutectic alloy) :
CMOS --> Al ; SPAD --> Ge
Established technology in MEMS foundry



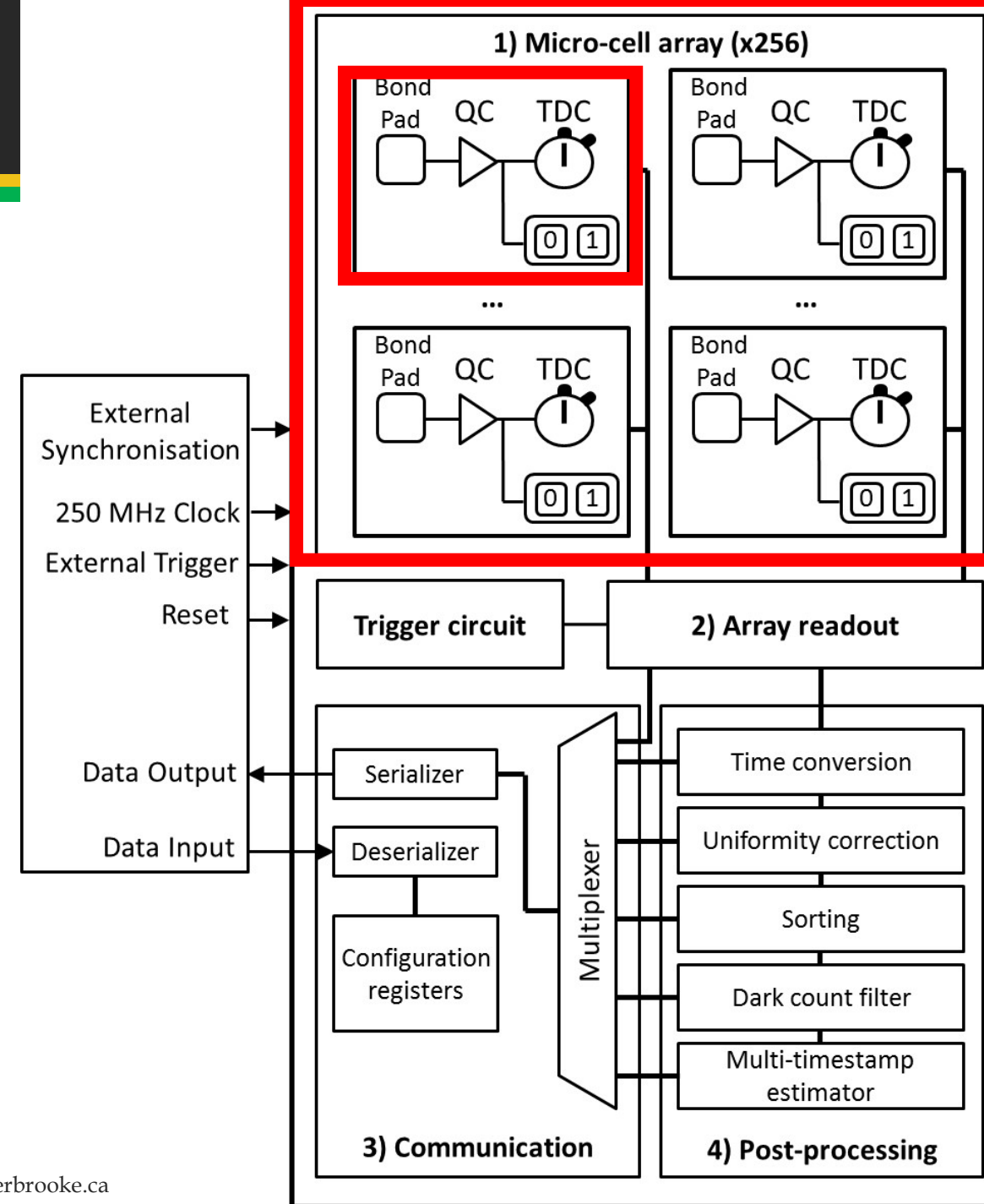
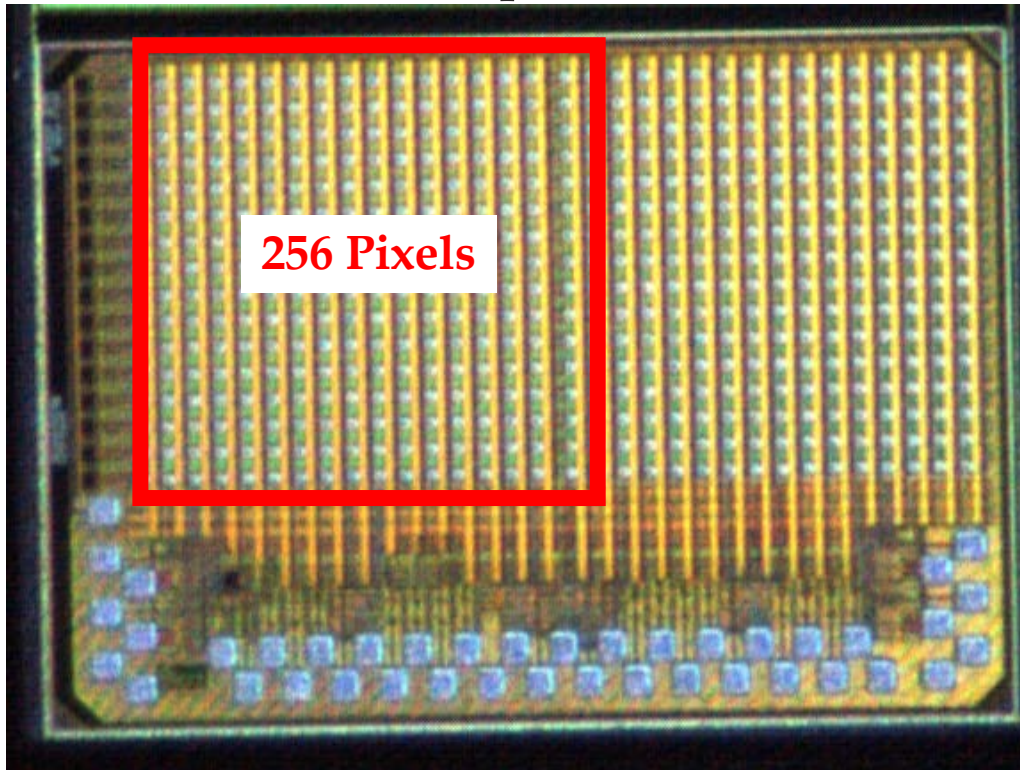
Development of the PDC Technology:

Microelectronic Readout Integrated Circuit for
Precise Single Photon Timing Resolution (Goal: sub 10 ps)

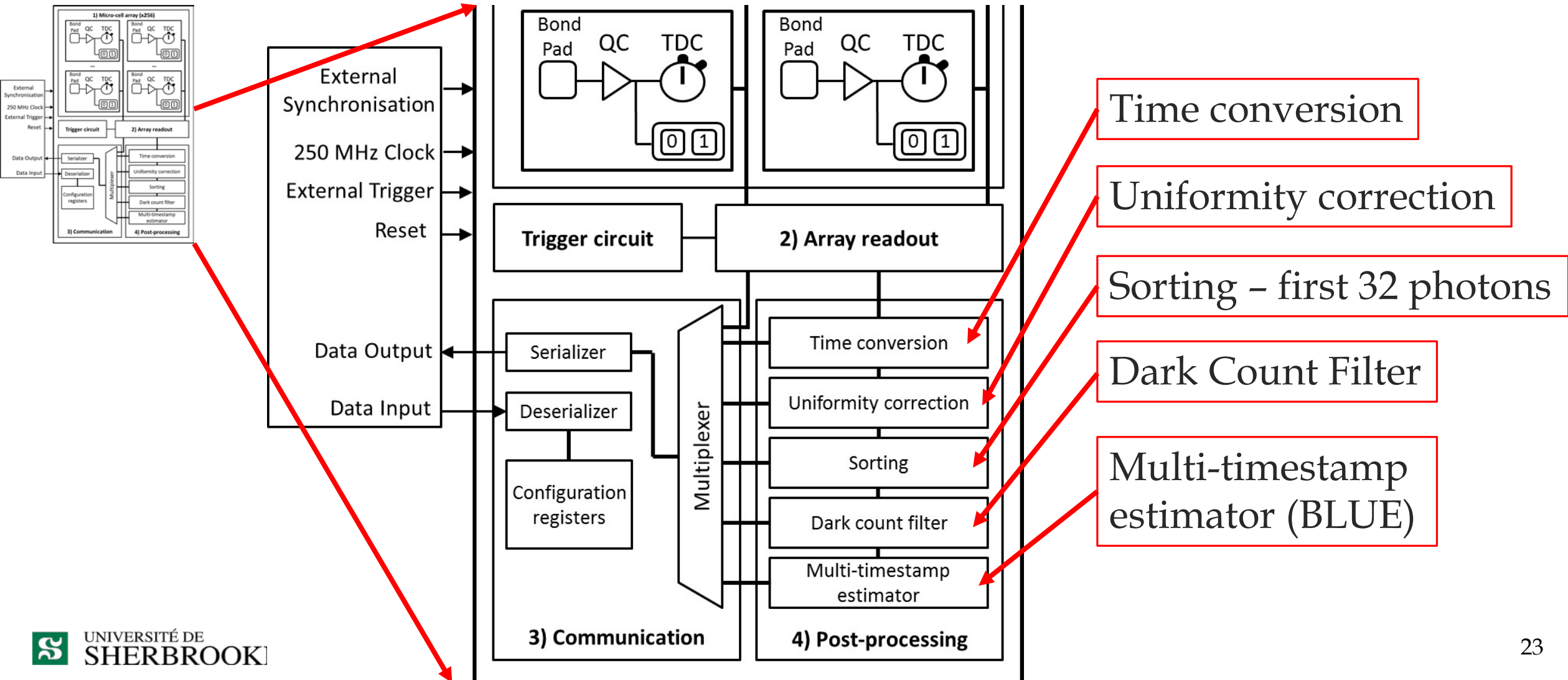


ASIC Overview (originally for PET)

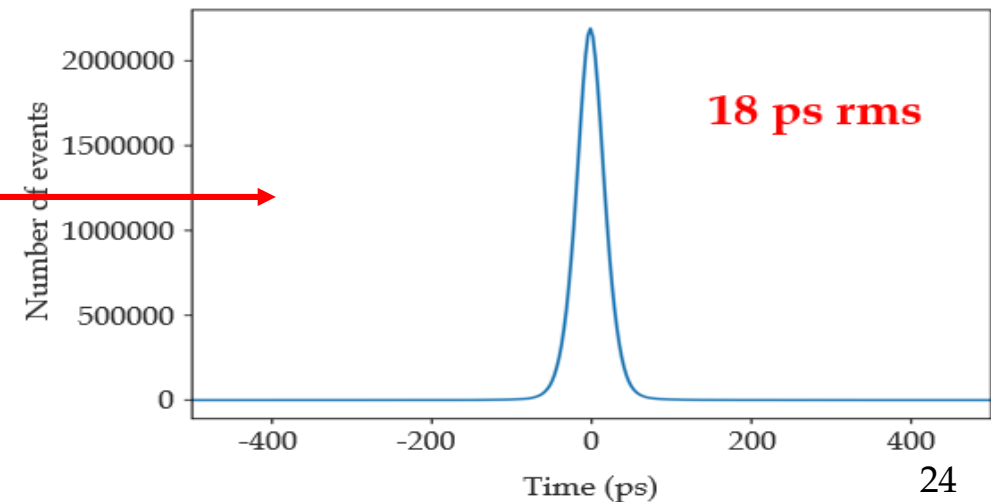
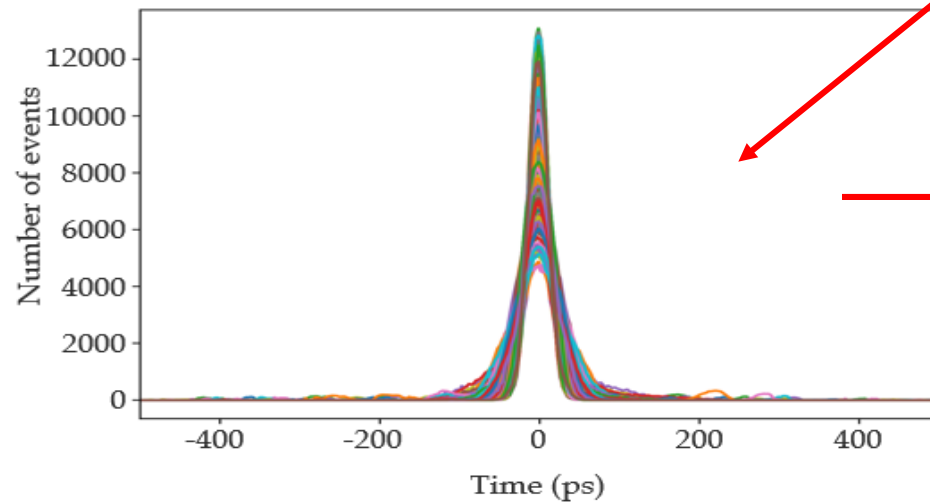
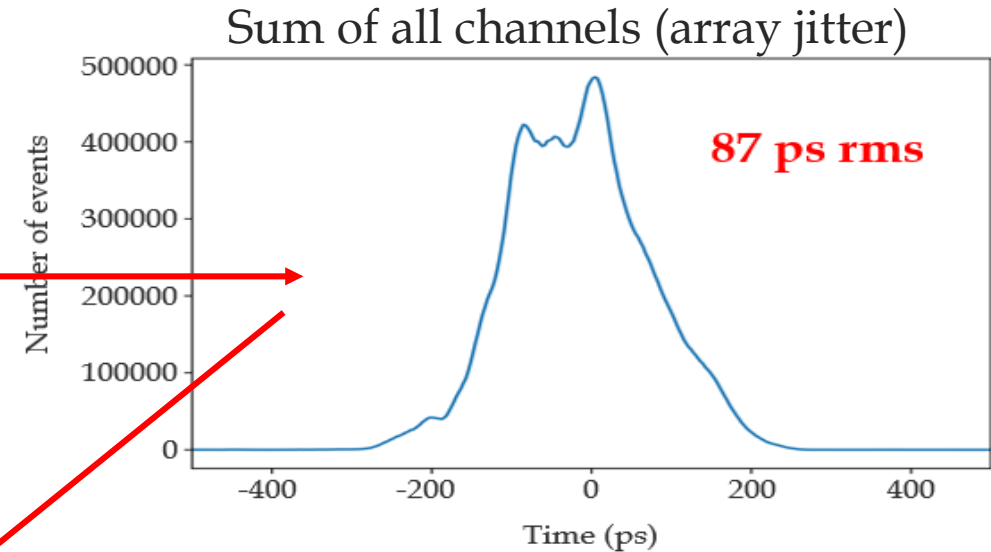
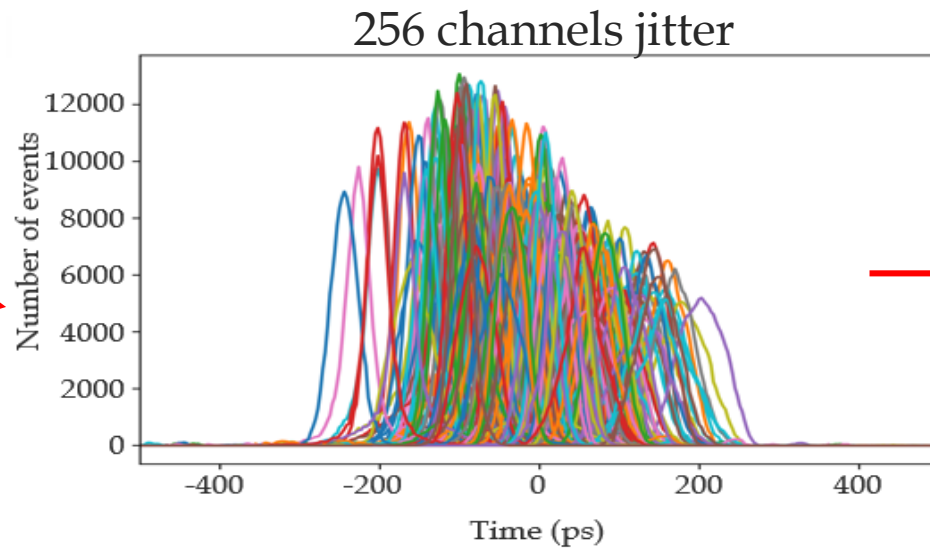
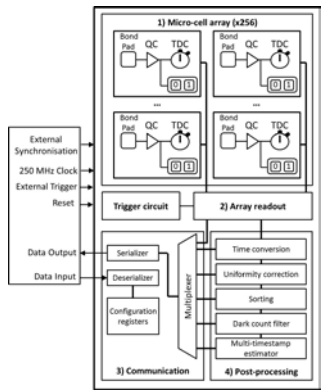
- TSMC 65 nm CMOS (GP)
- 16×16 pixels in $1.1 \times 1.1 \text{ mm}^2$ (red box)
- New revision May 2020 in fab
 - 1 TDC shared with 4 SPAD
 - LP instead of GP process flavor



Embedded Digital Signal Processing: Improved Coincidence Timing Resolution and Lower Output Data Bandwidth

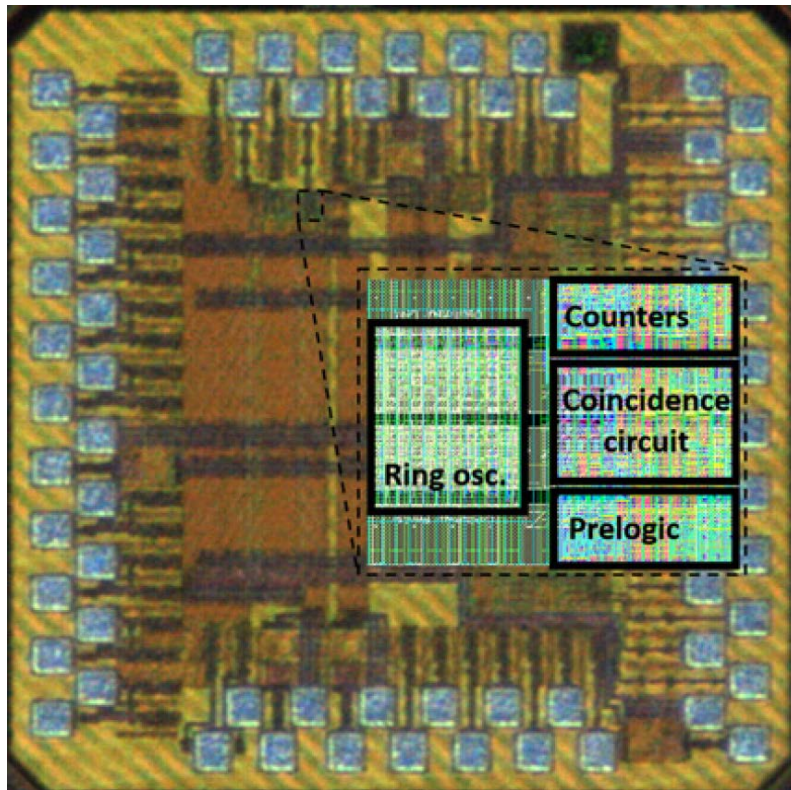


Integrated Circuit Embedded Digital Signal Processing Example: Uniformity Correction



Ring Oscillator based Vernier Time-to-Digital Converter

22 μ W, 5.1 ps LSB, 5.5 ps RMS jitter Vernier time-to-digital converter in CMOS 65 nm for single photon avalanche diode array, Electronics Letters, April 2020, Vol. 56 No. 9 pp. 424–426,
F. Nolet, N. Roy, S. Carrier, J. Bouchard, R. Fontaine, S.A. Charlebois and J.-F. Pratte



Parameter	This work	Ref. [3]	Ref. [7]	Ref. [5]
technology, nm	65	65	65	350
area, mm ²	0.00151	0.0013	0.068	0.3
LSB, ps	5.1	15	2.2	10
jitter, ps RMS	5.5	6.9	0.6	17.2
event rate, ME/s	1–8	3	2.2	0.3
power, μ W	22–41	160	2 300	15,000
pJ/event	22–5.1	32	46	5000
FoM	0.17–0.04	0.29	1.9	25,800
FoM = [Power (μ W) \times Jitter (ps RMS) \times Area (mm ²) / [Event Rate (Mevents/s)]				

$$\text{FOM} = \frac{\text{Power } (\mu\text{W}) \times \sigma_{\text{global}} \text{ (ps)} \times \text{Area } (\text{mm}^2)}{\text{Events Rate (Mevents/s)} \left[\text{pJ/event} \cdot \text{ps}_{\text{rms}} \cdot \text{mm}^2 \right]}. \quad (21)$$

Time-to-Digital Converters R&D

- New TDC architecture/concept developed
- Patent written. Final proof read. Should be submitted for evaluation before end of June 2020.

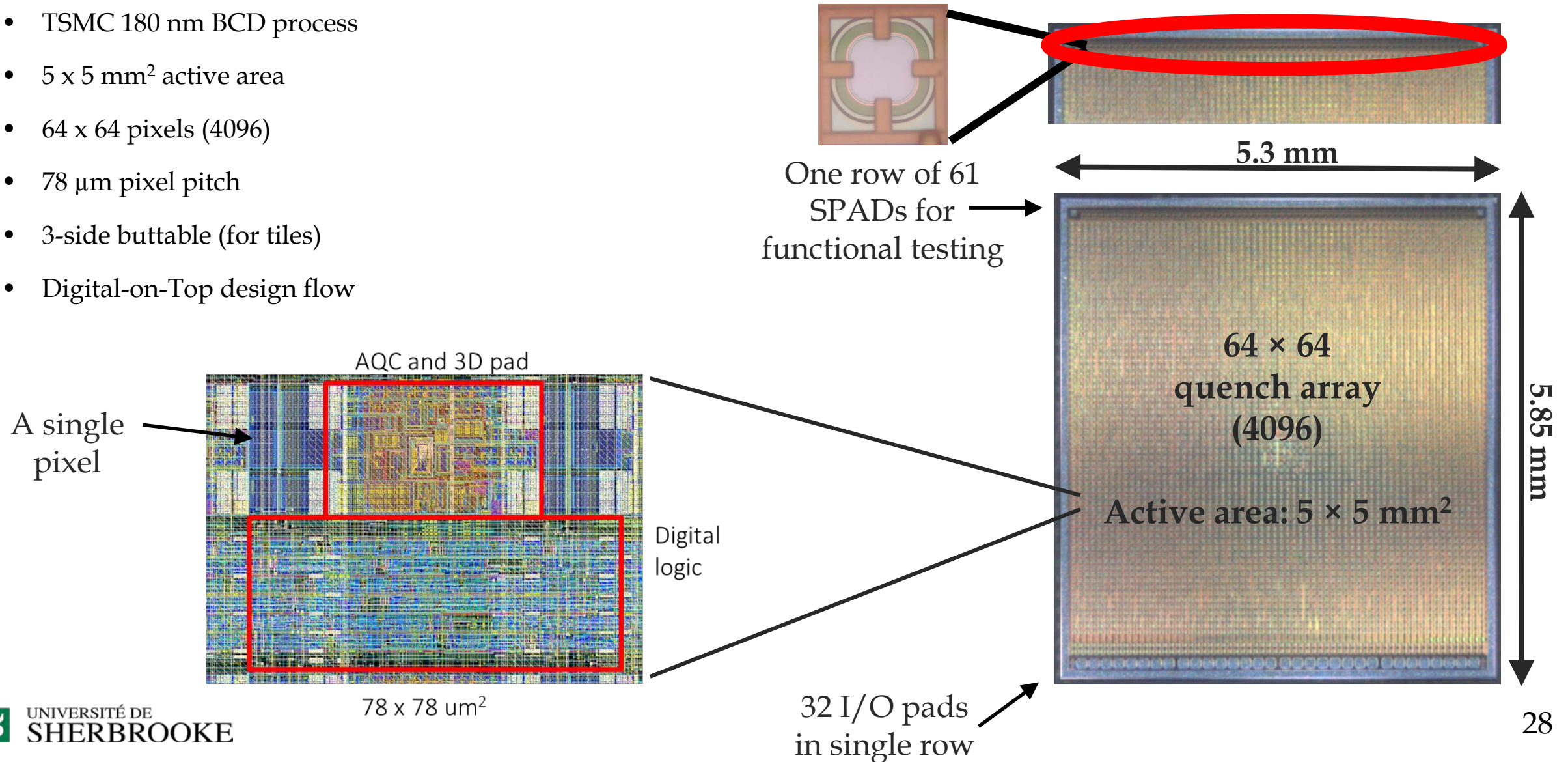
Development of the PDC Technology:

Microelectronic Readout Integrated Circuit for
Low Power PDC and Large Area Detectors

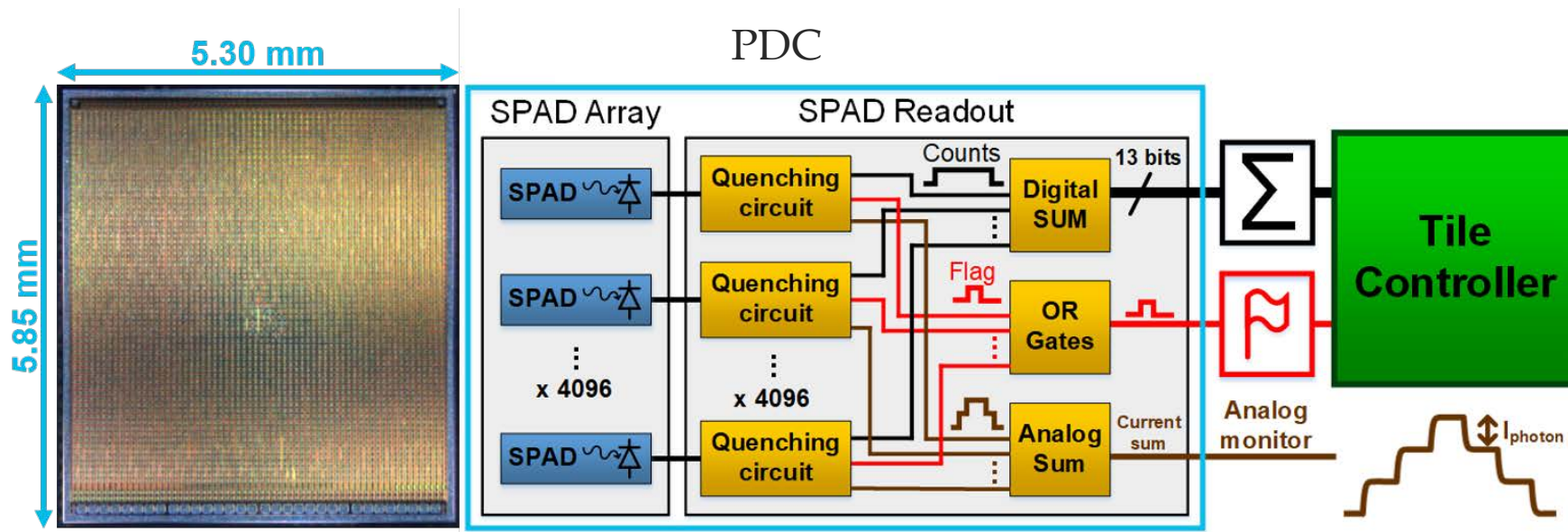


CMOS Readout for PDC – Overview

- TSMC 180 nm BCD process
- $5 \times 5 \text{ mm}^2$ active area
- 64×64 pixels (4096)
- $78 \mu\text{m}$ pixel pitch
- 3-side buttable (for tiles)
- Digital-on-Top design flow

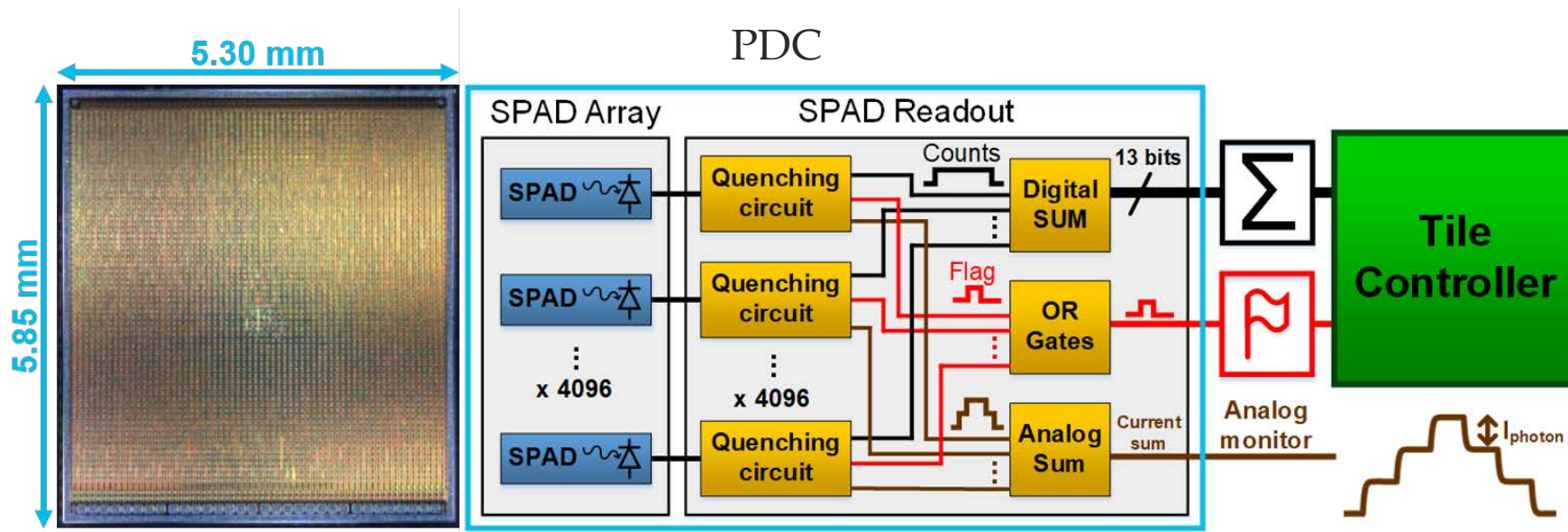


CMOS Readout for PDC – Low Power Architecture



CMOS Readout for PDC – Low Power Architecture

- nEXO operation mode: **INTEGRATION**
 - Event driven: each PDC signals the tile controller when a SPAD triggers
 - **Asynchronous (no event no clock – low power)**
 - Integration time from 10 ns to 10 μ s
 - Transmission of total counts (over integration time) when requested by the tile controller
 - Analog monitor for demonstration



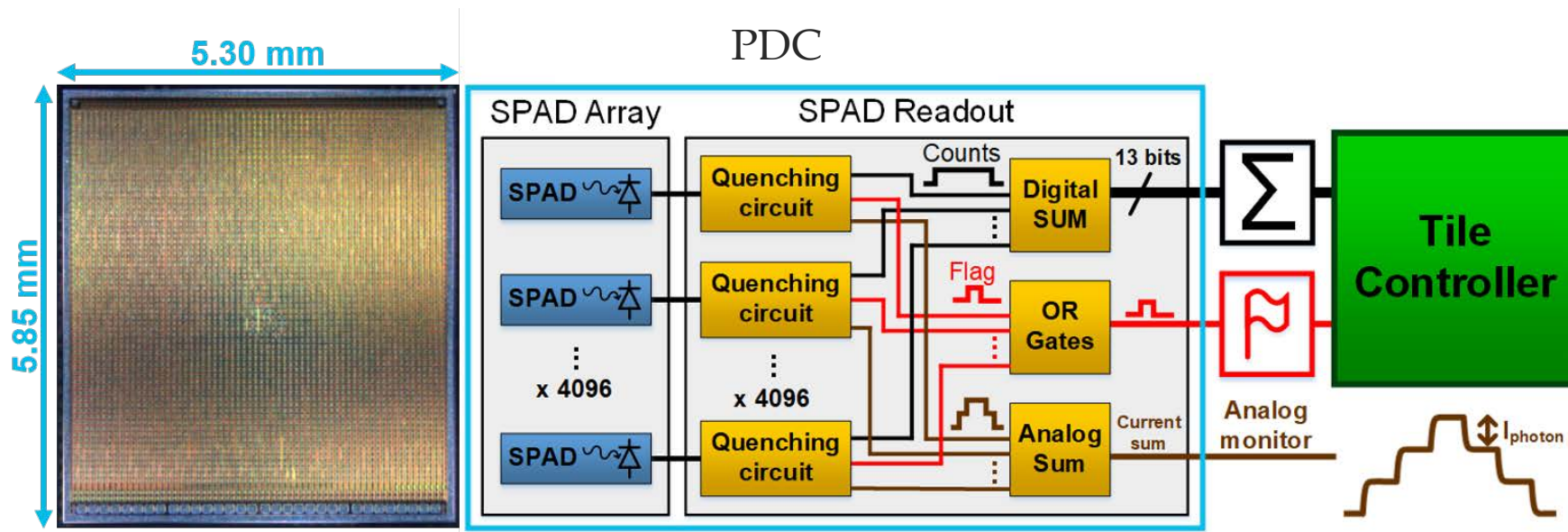
CMOS Readout for PDC – Low Power Architecture

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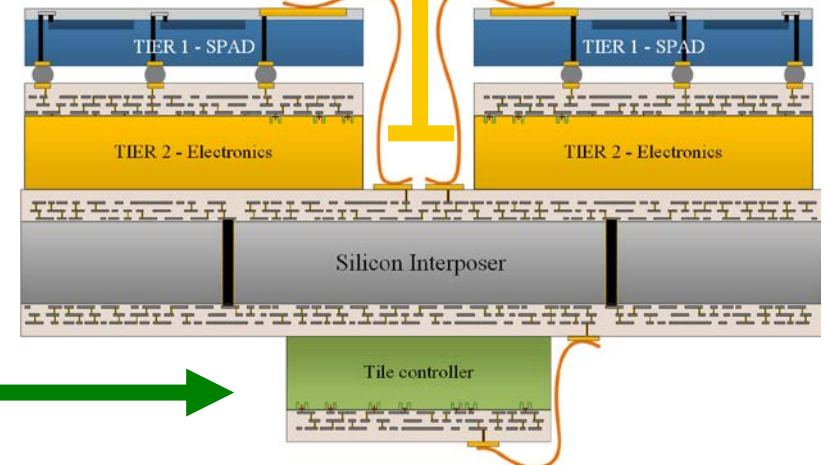
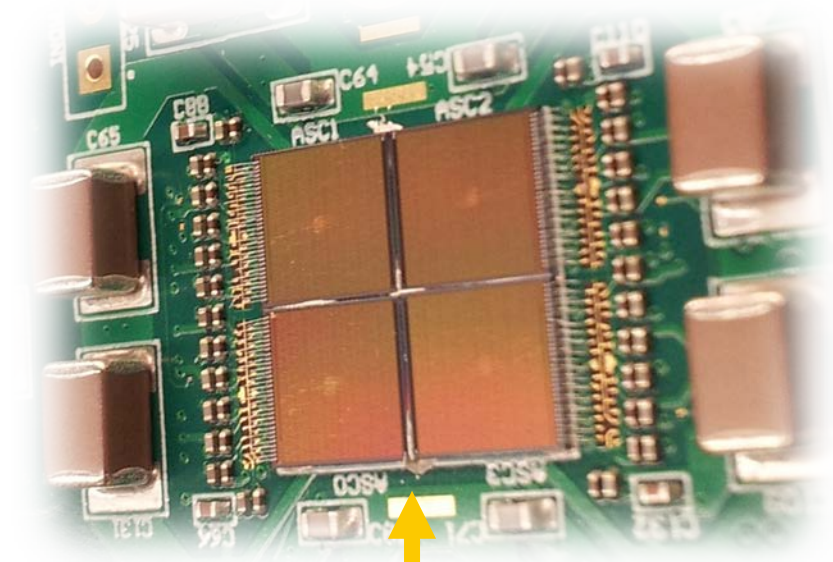
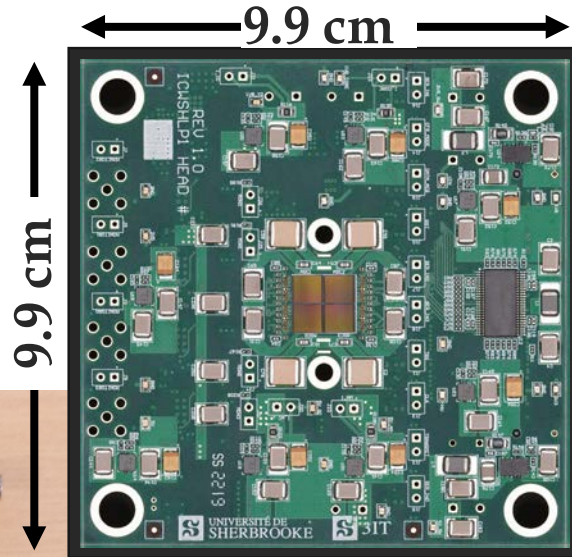
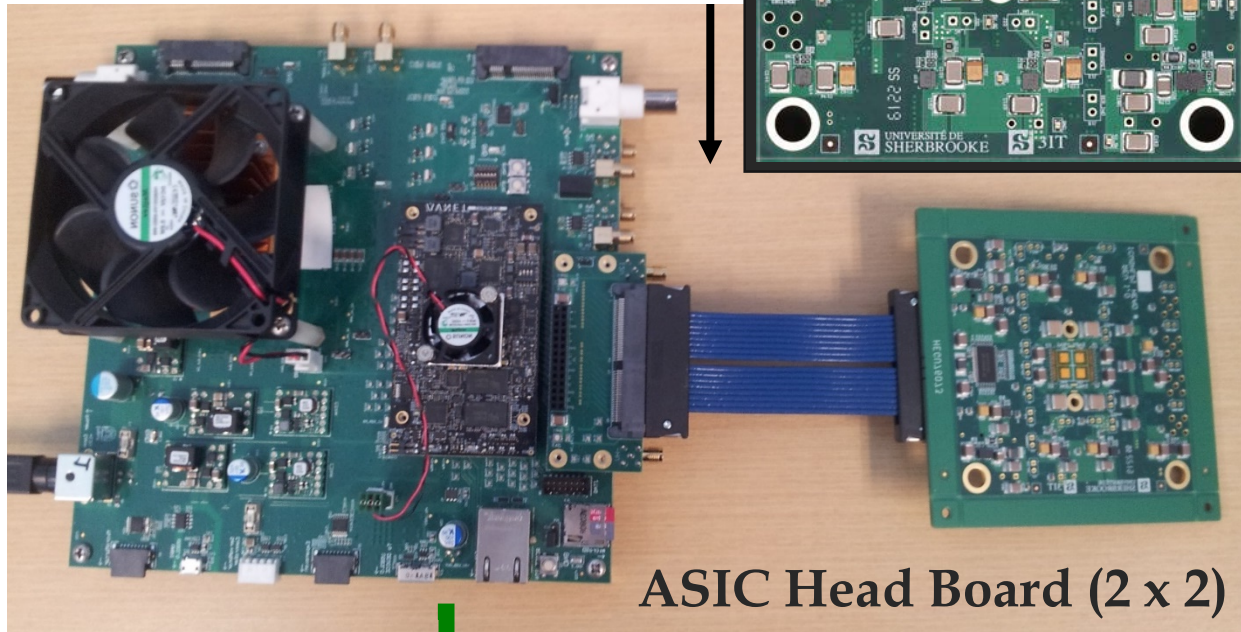
- LAr operation mode: **CONTINUOUS SAMPLING**

- Synchronous operation by a clock
- Flags the controller to signal counts
- Low flag jitter (<250 ps) to allow time-of-flight
- 128 FIFO depth for transmission on request
- FIFO sampling bins: short (10 ns) and long frames (1 μ s) to allow PSD (Pulse Shape Discrimination)



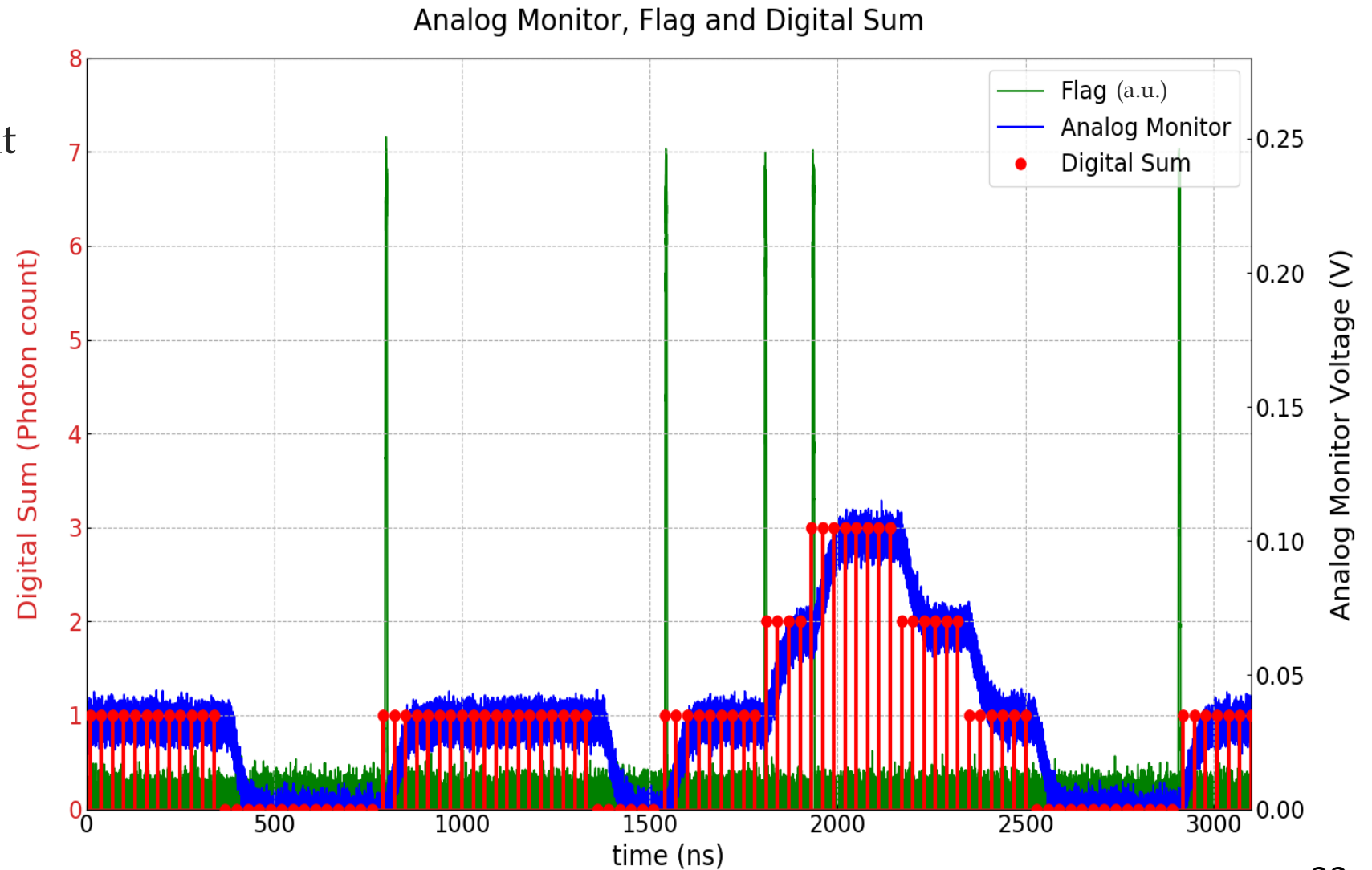
Measurement Testbench – Toward Tile Integration

Tile Controller:
UltraZed-EG SOM Board
(ARM + FPGA)



Photon-to-Digital Converter Measurements: Flag, Digital Sum and Analog Monitor Corroborated

- ADC like measurement
 - Number of pixels triggered at the moment of the acquisition
- Flag signals every detected event
- Analog monitor confirms the digital output
- 25.2 W / 4.5 m² for nEXO operation mode



Conclusion

- No fundamental limitation to build Front side illumination Photon-to-Digital Converter, but it is a great engineering challenge.
- First PDC expected in 2021.
- SPAD array, 3D integration and readout electronics developed and optimized in parallel.
 - Microelectronics readout for particle physics: wafer level production winter 2021.
 - SPAD R&D within Teledyne-DALSA.
 - New masks set in fabrication (optimized SPAD).
 - New SPAD arrays last March 2020: Covid-19 delay.
- PDC architecture flexible and versatile: they can be used/tailored for your application.
- (We are recruiting! Ph.D. and Postdoc.)
- Back side illumination SPAD array under design for VUV to NIR.

Selected Publications from our Team

- **Roadmap toward 10 ps time-of-flight PET challenge.** (2020). Lecoq, P.; Morel, C.; Pratte, J-F. et al. *Physics in Medicine and Biology*. Institute of Physics and engineering in Medicine.
- **22 μ W, 5.1 ps LSB, 5.5 ps RMS jitter Vernier time-to-digital converter in CMOS 65 nm for single photon avalanche diode array.** (2020). Nolet, F.; Roy, N.; Carrier, S.; Bouchard, J.; Fontaine, R.; Charlebois, S. A.; Pratte, J-F. *ELECTRONICS LETTERS*. 56(9): 424-426.
- **Embedded time of arrival estimation for digital photomultipliers with in-pixel TDCs.** (2020). Lemaire, W.; Nolet, F.; Dubois, F.; Corbeil Therrien, A.; Pratte, J-F.; Fontaine, R. *Nuclear Inst. And Methods in Physics Research*, A. 163538
- **Dark Count Resilient Time Estimators for Time-of-Flight PET.** (2020). Lemaire, W.; Corbeil Therrien, A.; Pratte, J-F.; Fontaine, R. *IEEE Transactions on Radiation and Plasma Medical Sciences*. 4(1): 24-29
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The End

